Freescale Semiconductor - MC908QT1ACFQE Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-EP (4x4)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908qt1acfqe

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Chapter 2
Memory

2.1 Introduction

The central processor unit (CPU08) can address 64 Kbytes of memory space. The memory map, shown in Figure 2-1.

2.2 Unimplemented Memory Locations

Executing code from an unimplemented location will cause an illegal address reset. In Figure 2-1, unimplemented locations are shaded.

2.3 Reserved Memory Locations

Accessing a reserved location can have unpredictable effects on MCU operation. In Figure 2-1, register locations are marked with the word Reserved or with the letter R.

2.4 Direct Page Registers

Figure 2-2 shows the memory mapped registers of the MC68HC908QYA/QTA Family. Registers with addresses between $0000 and $00FF are considered direct page registers and all instructions including those with direct page addressing modes can access them. Registers between $0100 and $FFFF require non-direct page addressing modes. See Chapter 7 Central Processor Unit (CPU) for more information on addressing modes.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$0028	TIM Channel 1 Status and Control Register (TSC1) See page 135.	Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
$0029	TIM Channel 1 Register High (TCH1H) See page 137.	Read: Write:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Reset:	Indeterminate after reset							
$002A	TIM Channel 1 Register Low (TCH1L) See page 137.	Read: Write:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Reset:	Indeterminate after reset							
$002B ↓ $0035	Reserved									
$0036	Oscillator Status and Control Register (OSCSC) See page 100.	Read: Write:	OSCOPT1	OSCOPT0	ICFS1	ICFS0	ECFS1	ECFS0	ECGON	ECGST
		Reset:	0	0	1	0	0	0	0	0
$0037	Reserved									
$0038	Oscillator Trim Register (OSCTRIM) See page 101.	Read: Write:	TRIM7	TRIM6	TRIM5	TRIM4	TRIM3	TRIM2	TRIM1	TRIM0
		Reset:	1	0	0	0	0	0	0	0
$0039 ↓ $003B	Reserved									
$003C	ADC10 Status and Control Register (ADSCR) See page 46.	Read: Write:	COCO	AIEN	ADCO	ADCH4	ADCH3	ADCH2	ADCH1	ADCH0
		Reset:	0	0	0	1	1	1	1	1
$003D	ADC10 Data Register High (ADRH) See page 48.	Read:	0	0	0	0	0	0	AD9	AD8
		Write:	R	R	R	R	R	R	R	R
		Reset:	0	0	0	0	0	0	0	0
$003E	ADC10 Data Register Low (ADRL) See page 48.	Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
		Write:	R	R	R	R	R	R	R	R
		Reset:	0	0	0	0	0	0	0	0
$003F	ADC10 Clock Register (ADCLK) See page 48.	Read: Write:	ADLPC	ADIV1	ADIV0	ADICLK	MODE1	MODE0	ADLSMP	ACLKEN
		Reset:	0	0	0	0	0	0	0	0

▒ = Unimplemented R = Reserved U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 3 of 5)

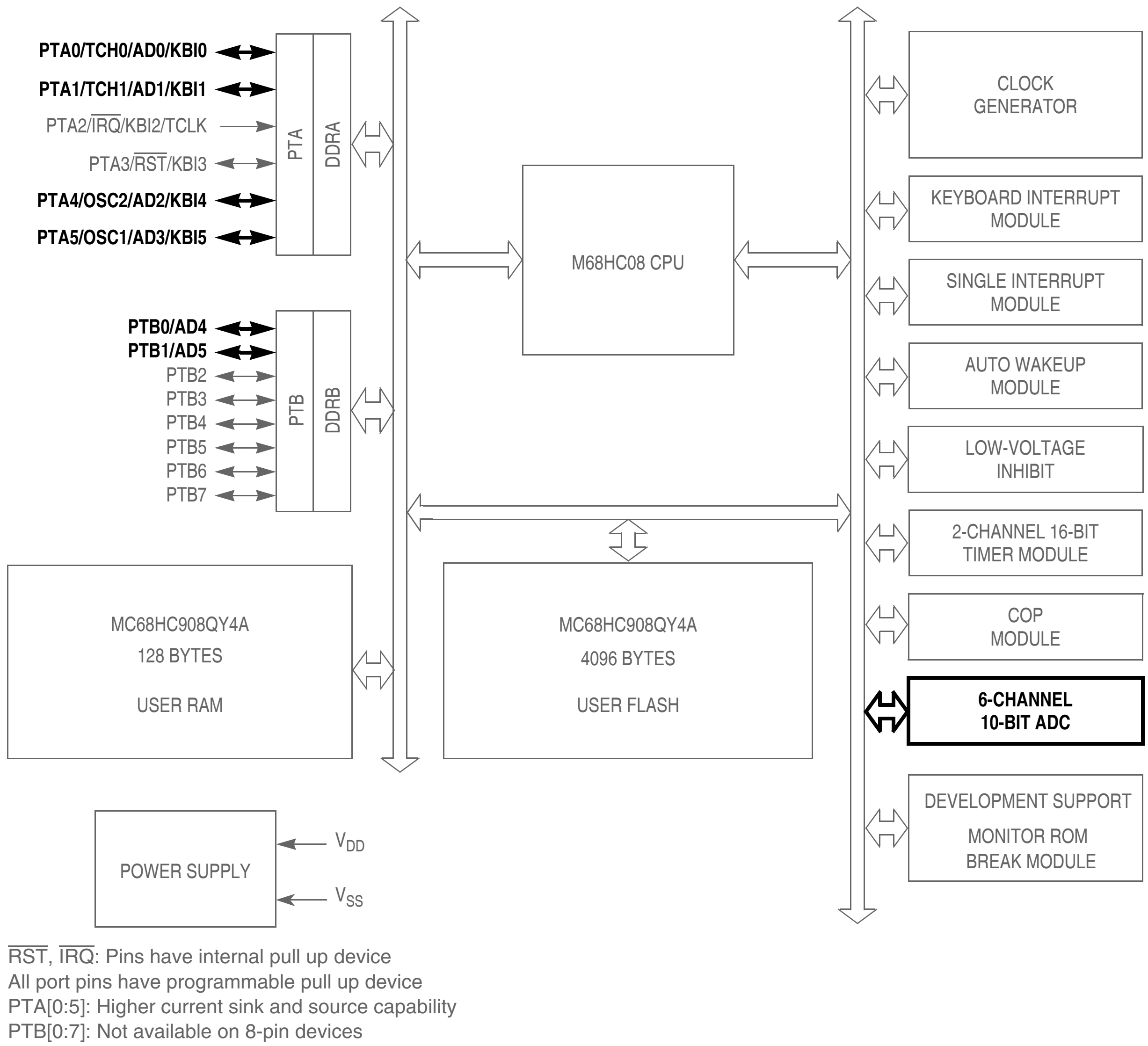


Figure 3-1. Block Diagram Highlighting ADC10 Block and Pins

Upon reset or when a conversion is otherwise aborted, the ADC10 module will enter a low power, inactive state. In this state, all internal clocks and references are disabled. This state is entered asynchronously and immediately upon aborting of a conversion.

3.3.3.4 Total Conversion Time

The total conversion time depends on many factors such as sample time, bus frequency, whether ACLKEN is set, and synchronization time. The total conversion time is summarized in Table 3-1.

Table 3-1. Total Conversion Time versus Control Conditions

Conversion Mode	ACLKEN	Maximum Conversion Time
8-Bit Mode (short sample — ADLSMP = 0):		
Single or 1st continuous	0	18 ADCK + 3 bus clock
Single or 1st continuous	1	18 ADCK + 3 bus clock + 5 µs
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	16 ADCK
8-Bit Mode (long sample — ADLSMP = 1):		
Single or 1st continuous	0	38 ADCK + 3 bus clock
Single or 1st continuous	1	38 ADCK + 3 bus clock + 5 µs
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	36 ADCK
10-Bit Mode (short sample — ADLSMP = 0):		
Single or 1st continuous	0	21 ADCK + 3 bus clock
Single or 1st continuous	1	21 ADCK + 3 bus clock + 5 µs
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	19 ADCK
10-Bit Mode (long sample — ADLSMP = 1):		
Single or 1st continuous	0	41 ADCK + 3 bus clock
Single or 1st continuous	1	41 ADCK + 3 bus clock + 5 µs
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	39 ADCK

The maximum total conversion time for a single conversion or the first conversion in continuous conversion mode is determined by the clock source chosen and the divide ratio selected. The clock source is selectable by the ADICLK and ACLKEN bits, and the divide ratio is specified by the ADIV bits. For example, if the alternate clock source is 16 MHz and is selected as the input clock source, the input clock divide-by-8 ratio is selected and the bus frequency is 4 MHz, then the conversion time for a single 10-bit conversion is:

$$\text{Maximum Conversion time} = \frac{\text{21 ADCK cycles}}{\text{16 MHz/8}} + \frac{\text{3 bus cycles}}{\text{4 MHz}} = 11.25\ \mu s$$

$$\text{Number of bus cycles} = 11.25\ \mu s \times 4\ \text{MHz} = 45\ \text{cycles}$$

NOTE

The ADCK frequency must be between f_{ADCK} minimum and f_{ADCK} maximum to meet A/D specifications.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	0	0	0	0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 3-4. ADC10 Data Register High (ADRH), 8-Bit Mode

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	0	0	AD9	AD8
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 3-5. ADC10 Data Register High (ADRH), 10-Bit Mode

3.8.3 ADC10 Result Low Register (ADRL)

This register holds the LSBs of the result. This register is updated each time a conversion completes. Reading ADRH prevents the ADC10 from transferring subsequent conversion results into the result registers until ADRL is read. If ADRL is not read until the after next conversion is completed, then the intermediate conversion result will be lost. In 8-bit mode, there is no interlocking with ADRH.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 3-6. ADC10 Data Register Low (ADRL)

3.8.4 ADC10 Clock Register (ADCLK)

This register selects the clock frequency for the ADC10 and the modes of operation.

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	ADLPC	ADIV1	ADIV0	ADICLK	MODE1	MODE0	ADLSMP	ACLKEN
Reset:	0	0	0	0	0	0	0	0

Figure 3-7. ADC10 Clock Register (ADCLK)

ADLPC — ADC10 Low-Power Configuration Bit

ADLPC controls the speed and power configuration of the successive approximation converter. This is used to optimize power consumption when higher sample rates are not required.

1 = Low-power configuration: The power is reduced at the expense of maximum clock speed.
0 = High-speed configuration

IRQPUD — $\overline{\text{IRQ}}$ Pin Pullup Control Bit

1 = Internal pullup is disconnected
0 = Internal pullup is connected between $\overline{\text{IRQ}}$ pin and V_{DD}

IRQEN — $\overline{\text{IRQ}}$ Pin Function Selection Bit

1 = Interrupt request function active in pin
0 = Interrupt request function inactive in pin

OSCENINSTOP— Oscillator Enable in Stop Mode Bit

OSCENINSTOP, when set, will allow the clock source to continue to generate clocks in stop mode. This function can be used to keep the auto-wakeup running while the rest of the microcontroller stops. When clear, the clock source is disabled when the microcontroller enters stop mode.

1 = Oscillator enabled to operate during stop mode
0 = Oscillator disabled during stop mode

RSTEN — $\overline{\text{RST}}$ Pin Function Selection

1 = Reset function active in pin
0 = Reset function inactive in pin

NOTE

The RSTEN bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVITRIP	SSREC	STOP	COPD
Reset:	0	0	0	0	U	0	0	0
POR:	0	0	0	0	0	0	0	0

U = Unaffected

Figure 5-2. Configuration Register 1 (CONFIG1)

COPRS (Out of Stop Mode) — COP Reset Period Selection Bit

1 = COP reset short cycle = 8176 × BUSCLKX4
0 = COP reset long cycle = 262,128 × BUSCLKX4

COPRS (In Stop Mode) — Auto Wakeup Period Selection Bit, depends on OSCSTOPEN in CONFIG2 and external clock source

1 = Auto wakeup short cycle = 512 × (INTRCOSC or BUSCLKX2)
0 = Auto wakeup long cycle = 16,384 × (INTRCOSC or BUSCLKX2)

LVISTOP — LVI Enable in Stop Mode Bit

When the LVIPWRD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP.

1 = LVI enabled during stop mode
0 = LVI disabled during stop mode

LVIRSTD — LVI Reset Disable Bit

LVIRSTD disables the reset signal from the LVI module.

1 = LVI module resets disabled
0 = LVI module resets enabled

8.4 Interrupts

The following IRQ source can generate interrupt requests:

- Interrupt flag (IRQF) — The IRQF bit is set when the $\overline{IRQ}$ pin is asserted based on the IRQ mode. The IRQ interrupt mask bit, IMASK, is used to enable or disable IRQ interrupt requests.

8.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

8.5.1 Wait Mode

The IRQ module remains active in wait mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of wait mode.

8.5.2 Stop Mode

The IRQ module remains active in stop mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of stop mode.

8.6 IRQ Module During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

8.7 I/O Signals

The IRQ module does not share its pin with any module on this MCU.

8.7.1 IRQ Input Pins ($\overline{IRQ}$)

The $\overline{IRQ}$ pin provides a maskable external interrupt source. The $\overline{IRQ}$ pin contains an internal pullup device.

Chapter 12
Input/Output Ports (PORTS)

12.1 Introduction

The MC68HC08QY1A, MC68HC08QY2A and MC68HC08QY4A have thirteen bidirectional input-output (I/O) pins and one input only pin. The MC68HC08QT1A, MC68HC08QT2A and MC68HC08QT4A has five bidirectional I/O pins and one input only pin. All I/O pins are programmable as inputs or outputs.

12.2 Unused Pin Termination

Input pins and I/O port pins that are not used in the application must be terminated. This prevents excess current caused by floating inputs, and enhances immunity during noise or transient events. Termination methods include:

1. Configuring unused pins as outputs and driving high or low;
2. Configuring unused pins as inputs and enabling internal pull-ups;
3. Configuring unused pins as inputs and using external pull-up or pull-down resistors.

Never connect unused pins directly to V_{DD} or V_{SS}.

Since some general-purpose I/O pins are not available on all packages, these pins must be terminated as well. Either method 1 or 2 above are appropriate.

12.3 Port A

Port A is an 6-bit special function port that shares its pins with the keyboard interrupt (KBI) module (see Chapter 9 Keyboard Interrupt Module (KBI), the 2-channel timer interface module (TIM) (see Chapter 14 Timer Interface Module (TIM)), the 10-bit ADC (see Chapter 3 Analog-to-Digital Converter (ADC10) Module), the external interrupt (IRQ) pin (see Chapter 8 External Interrupt (IRQ)), the reset (RST) pin enabled using a configuration register (see Chapter 5 Configuration Register (CONFIG)) and the oscillator pins (see Chapter 11 Oscillator (OSC) Module).

Each port A pin also has a software configurable pullup device if the corresponding port pin is configured as an input port.

NOTE

PTA2 is input only.

When the $\overline{IRQ}$ function is enabled in the configuration register 2 (CONFIG2), bit 2 of the port A data register (PTA) will always read a logic 0. In this case, the BIH and BIL instructions can be used to read the logic level on the PTA2 pin. When the $\overline{IRQ}$ function is disabled, these instructions will behave as if the PTA2 pin is a logic 1. However, reading bit 2 of PTA will read the actual logic level on the pin.

13.6.2.1 Interrupt Status Register 1

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF6	IF5	IF4	IF3	IF2	IF1	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-11. Interrupt Status Register 1 (INT1)

IF1–IF6 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 13-3.

1 = Interrupt request present

0 = No interrupt request present

Bit 0, 1 — Always read 0

13.6.2.2 Interrupt Status Register 2

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF14	IF13	IF12	IF11	IF10	IF9	IF8	IF7
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-12. Interrupt Status Register 2 (INT2)

IF7–IF14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in Table 13-3.

1 = Interrupt request present

0 = No interrupt request present

13.6.2.3 Interrupt Status Register 3

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF22	IF21	IF20	IF19	IF18	IF17	IF16	IF15
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 13-13. Interrupt Status Register 3 (INT3)

IF15–IF22 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 13-3.

1 = Interrupt request present

0 = No interrupt request present

13.6.3 Reset

All reset sources always have equal and highest priority and cannot be arbitrated.

13.6.4 Break Interrupts

The break module can stop normal program flow at a software programmable break point by asserting its break interrupt output. (See Chapter 15 Development Support.) The SIM puts the CPU into the break state by forcing it to the SWI vector location. Refer to the break interrupt subsection of each module to see how each module is affected by the break state.

13.6.5 Status Flag Protection in Break Mode

The SIM controls whether status flags contained in other modules can be cleared during break mode. The user can select whether flags are protected from being cleared by properly initializing the break clear flag enable bit (BCFE) in the break flag control register (BFCR).

Protecting flags in break mode ensures that set flags will not be cleared while in break mode. This protection allows registers to be freely read and written during break mode without losing status flag information.

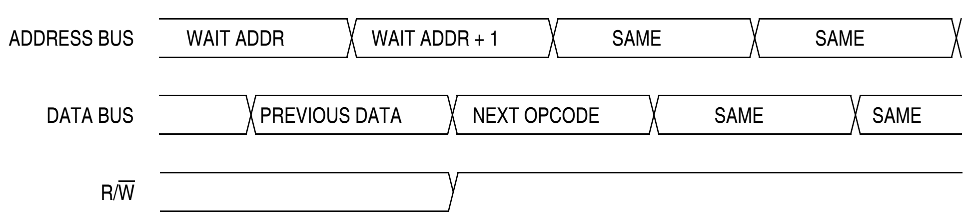
Setting the BCFE bit enables the clearing mechanisms. Once cleared in break mode, a flag remains cleared even when break mode is exited. Status flags with a two-step clearing mechanism — for example, a read of one register followed by the read or write of another — are protected, even when the first step is accomplished prior to entering break mode. Upon leaving break mode, execution of the second step will clear the flag as normal.

13.7 Low-Power Modes

Executing the WAIT or STOP instruction puts the MCU in a low power- consumption mode for standby situations. The SIM holds the CPU in a non-clocked state. The operation of each of these modes is described below. Both STOP and WAIT clear the interrupt mask (I) in the condition code register, allowing interrupts to occur.

13.7.1 Wait Mode

In wait mode, the CPU clocks are inactive while the peripheral clocks continue to run. Figure 13-14 shows the timing for wait mode entry.



NOTE: Previous data can be operand data or the WAIT opcode, depending on the last instruction.

Figure 13-14. Wait Mode Entry Timing

A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred.

The value in the TIM channel registers determines the pulse width of the PWM output. The pulse width of an 8-bit PWM signal is variable in 256 increments. Writing $0080 (128) to the TIM channel registers produces a duty cycle of 128/256 or 50%.

14.3.4.1 Unbuffered PWM Signal Generation

Any output compare channel can generate unbuffered PWM pulses as described in 14.3.4 Pulse Width Modulation (PWM). The pulses are unbuffered because changing the pulse width requires writing the new pulse width value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change a pulse width value could cause incorrect operation for up to two PWM periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that PWM period. Also, using a TIM overflow interrupt routine to write a new, smaller pulse width value may cause the compare to be missed. The TIM may pass the new value before it is written to the timer channel (TCHxH:TCHxL).

Use the following methods to synchronize unbuffered changes in the PWM pulse width on channel x:

- When changing to a shorter pulse width, enable channel x output compare interrupts and write the new value in the output compare interrupt routine. The output compare interrupt occurs at the end of the current pulse. The interrupt routine has until the end of the PWM period to write the new value.
- When changing to a longer pulse width, enable TIM overflow interrupts and write the new value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the current PWM period. Writing a larger value in an output compare interrupt routine (at the end of the current pulse) could cause two output compares to occur in the same PWM period.

NOTE

In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error or noise. Toggling on output compare also can cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.

14.3.4.2 Buffered PWM Signal Generation

Channels 0 and 1 can be linked to form a buffered PWM channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The TIM channel 0 registers initially control the pulse width on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the pulse width at the beginning of the next PWM period. At each subsequent overflow, the TIM channel registers (0 or 1) that control the pulse width are the ones written to last. TSC0 controls and monitors the buffered PWM function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered PWM signal generation, do not write new pulse width values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active

Setting MS0B causes the contents of TSC1 to be ignored by the TIM and reverts TCH1 to general-purpose I/O.

1 = Buffered output compare/PWM operation enabled
0 = Buffered output compare/PWM operation disabled

MSxA — Mode Select Bit A

When ELSxB:A ≠ 00, this read/write bit selects either input capture operation or unbuffered output compare/PWM operation. See Table 14-2.

1 = Unbuffered output compare/PWM operation
0 = Input capture operation

When ELSxB:A = 00, this read/write bit selects the initial output level of the TCHx pin (see Table 14-2).

1 = Initial output level low
0 = Initial output level high

NOTE

Before changing a channel function by writing to the MSxB or MSxA bit, set the TSTOP and TRST bits in the TIM status and control register (TSC).

ELSxB and ELSxA — Edge/Level Select Bits

When channel x is an input capture channel, these read/write bits control the active edge-sensing logic on channel x.

When channel x is an output compare channel, ELSxB and ELSxA control the channel x output behavior when an output compare occurs.

When ELSxB and ELSxA are both clear, channel x is not connected to an I/O port, and pin TCHx is available as a general-purpose I/O pin. Table 14-2 shows how ELSxB and ELSxA work.

Table 14-2. Mode, Edge, and Level Selection

MSxB	MSxA	ELSxB	ELSxA	Mode	Configuration
X	0	0	0	Output preset	Pin under port control; initial output level high
X	1	0	0		Pin under port control; initial output level low
0	0	0	1	Input capture	Capture on rising edge only
0	0	1	0		Capture on falling edge only
0	0	1	1		Capture on rising or falling edge
0	1	0	0	Output compare or PWM	Software compare only
0	1	0	1		Toggle output on compare
0	1	1	0		Clear output on compare
0	1	1	1		Set output on compare
1	X	0	1	Buffered output compare or buffered PWM	Toggle output on compare
1	X	1	0		Clear output on compare
1	X	1	1		Set output on compare

NOTE

After initially enabling a TIM channel register for input capture operation and selecting the edge sensitivity, clear CHxF to ignore any erroneous edge detection flags.

Chapter 15
Development Support

15.1 Introduction

This section describes the break module, the monitor module (MON), and the monitor mode entry methods.

15.2 Break Module (BRK)

The break module can generate a break interrupt that stops normal program flow at a defined address to enter a background program.

Features include:

- Accessible input/output (I/O) registers during the break Interrupt
- Central processor unit (CPU) generated break interrupts
- Software-generated break interrupts
- Computer operating properly (COP) disabling during break interrupts

15.2.1 Functional Description

When the internal address bus matches the value written in the break address registers, the break module issues a breakpoint signal ($\overline{\text{BKPT}}$) to the system integration module (SIM). The SIM then causes the CPU to load the instruction register with a software interrupt instruction (SWI). The program counter vectors to $FFFC and $FFFD ($FEFC and $FEFD in monitor mode).

The following events can cause a break interrupt to occur:

- A CPU generated address (the address in the program counter) matches the contents of the break address registers.
- Software writes a 1 to the BRKA bit in the break status and control register.

When a CPU generated address matches the contents of the break address registers, the break interrupt is generated. A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the microcontroller unit (MCU) to normal operation.

Figure 15-2 shows the structure of the break module.

When the internal address bus matches the value written in the break address registers or when software writes a 1 to the BRKA bit in the break status and control register, the CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with $FFFC and $FFFD ($FEFC and $FEFD in monitor mode)

16.5 5-V DC Electrical Characteristics

Characteristic[1]	Symbol	Min	Typ[2]	Max	Unit
Output high voltage I_{Load} = –2.0 mA, all I/O pins I_{Load} = –10.0 mA, all I/O pins I_{Load} = –15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OH}	V_{DD}–0.4 V_{DD}–1.5 V_{DD}–0.8	— — —	— — —	V
Maximum combined I_{OH} (all I/O pins)	I_{OHT}	—	—	50	mA
Output low voltage I_{Load} = 1.6 mA, all I/O pins I_{Load} = 10.0 mA, all I/O pins I_{Load} = 15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OL}	— — —	— — —	0.4 1.5 0.8	V
Maximum combined I_{OL} (all I/O pins)	I_{OHL}	—	—	50	mA
Input high voltage PTA0–PTA5, PTB0–PTB7	V_{IH}	0.7 x V_{DD}	—	V_{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V_{IL}	V_{SS}	—	0.3 x V_{DD}	V
Input hysteresis[3]	V_{HYS}	0.06 x V_{DD}	—	—	V
DC injection current, all ports[4]	I_{INJ}	–2	—	+2	mA
Total dc current injection (sum of all I/O)[4]	I_{INJTOT}	–25	—	+25	mA
Ports Hi-Z leakage current	I_{IL}	–1	±0.1	+1	µA
Capacitance Ports (as input)[3]	C_{IN}	—	—	8	pF
POR rearm voltage	V_{POR}	750	—	—	mV
POR rise time ramp rate[3][5]	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage [3]	V_{TST}	V_{DD} + 2.5	—	9.1	V
Pullup resistors[6] PTA0–PTA5, PTB0–PTB7	R_{PU}	16	26	36	kΩ
Pulldown resistors[7] PTA0–PTA5	R_{PD}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V_{TRIPF}	3.90	4.20	4.50	V
Low-voltage inhibit reset, trip rising voltage	V_{TRIPR}	4.00	4.30	4.60	V
Low-voltage inhibit reset/recover hysteresis	V_{HYS}	—	100	—	mV

1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.
3. Values are based on characterization results, not tested in production.
4. Guaranteed by design, not tested in production.
5. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
6. R_{PU} is measured at V_{DD} = 5.0 V.
7. R_{PD} is measured at V_{DD} = 5.0 V, Pulldown resistors only available when KBIx is enabled with KBIxPOL =1.

16.8 3-V DC Electrical Characteristics

Characteristic(1)	Symbol	Min	Typ(2)	Max	Unit
Output high voltage I_{Load} = –0.6 mA, all I/O pins I_{Load} = –4.0 mA, all I/O pins I_{Load} = –10.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OH}	V_{DD}–0.3 V_{DD}–1.0 V_{DD}–0.8	— — —	— — —	V
Maximum combined I_{OH} (all I/O pins)	I_{OHT}	—	—	50	mA
Output low voltage I_{Load} = 0.5 mA, all I/O pins I_{Load} = 6.0 mA, all I/O pins I_{Load} = 10.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OL}	— — —	— — —	0.3 1.0 0.8	V
Maximum combined I_{OL} (all I/O pins)	I_{OHL}	—	—	50	mA
Input high voltage PTA0–PTA5, PTB0–PTB7	V_{IH}	0.7 x V_{DD}	—	V_{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V_{IL}	V_{SS}	—	0.3 x V_{DD}	V
Input hysteresis(3)	V_{HYS}	0.06 x V_{DD}	—	—	V
DC injection current, all ports(4)	I_{INJ}	–2	—	+2	mA
Total dc current injection (sum of all I/O)(4)	I_{INJTOT}	–25	—	+25	mA
Ports Hi-Z leakage current	I_{IL}	–1	±0.1	+1	μA
Capacitance Ports (as input)(3)	C_{IN}	—	—	8	pF
POR rearm voltage	V_{POR}	750	—	—	mV
POR rise time ramp rate(3)(5)	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage (3)	V_{TST}	V_{DD} + 2.5	—	V_{DD} + 4.0	V
Pullup resistors(6) PTA0–PTA5, PTB0–PTB7	R_{PU}	16	26	36	kΩ
Pulldown resistors(7) PTA0–PTA5	R_{PD}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V_{TRIPF}	2.40	2.55	2.70	V
Low-voltage inhibit reset, trip rising voltage(6)	V_{TRIPR}	2.475	2.625	2.775	V
Low-voltage inhibit reset/recover hysteresis	V_{HYS}	—	75	—	mV

1. V_{DD} = 2.7 to 3.3 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.
3. Values are based on characterization results, not tested in production.
4. Guaranteed by design, not tested in production.
5. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
6. R_{PU} is measured at V_{DD} = 3.0 V
7. R_{PD} is measured at V_{DD} = 3.0 V, Pulldown resistors only available when KBIx is enabled with KBIxPOL =1.

16.10 3-V Control Timing

Characteristic(1)	Symbol	Min	Max	Unit
Internal operating frequency	f_{OP} (f_{Bus})	—	4	MHz
Internal clock period (1/f_{OP})	t_{cyc}	250	—	ns
$\overline{\text{RST}}$ input pulse width low(2)	t_{RL}	200	—	ns
$\overline{\text{IRQ}}$ interrupt pulse width low (edge-triggered)(2)	t_{ILIH}	200	—	ns
$\overline{\text{IRQ}}$ interrupt pulse period(2)	t_{ILIL}	Note(3)	—	t_{cyc}

1. V_{DD} = 2.7 to 3.3 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H; timing shown with respect to 20% V_{DD} and 70% V_{DD}, unless otherwise noted.
2. Values are based on characterization results, not tested in production.
3. The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1 t_{cyc}.

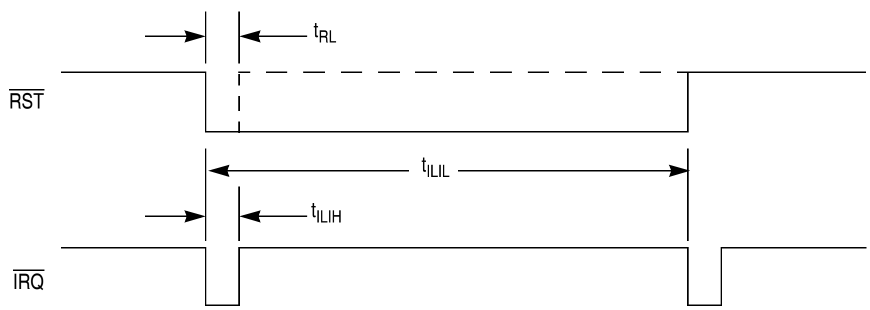


Figure 16-6. $\overline{\text{RST}}$ and $\overline{\text{IRQ}}$ Timing

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